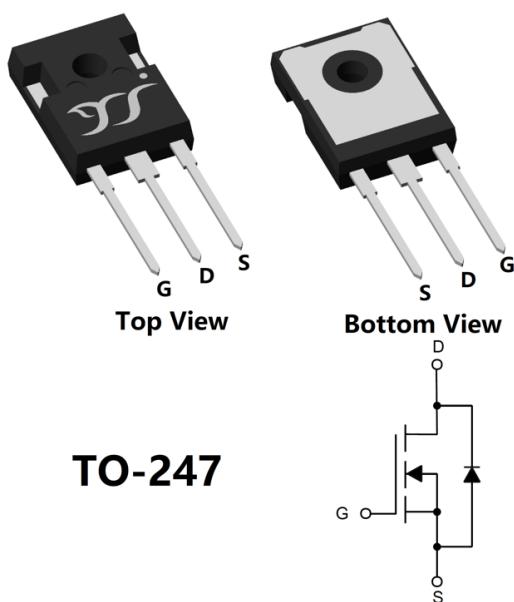




N-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} 100V
- I_D 280A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) <2.6mΩ
- $R_{DS(ON)}$ (at $V_{GS}=6V$) <3.0mΩ
- 100% EAS Tested
- 100% ∇V_{DS} Tested

General Description

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Load switch
- Battery management
- Solar

■ Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	V_{DS}	100	V
Gate-source Voltage	V_{GS}	± 20	V
Drain Current	I_D	20	A
		12	
		280	
		177	
Pulsed Drain Current ^A	I_{DM}	1100	A
Avalanche energy ^B	EAS	562	mJ
Total Power Dissipation ^C	P_D	3.4	W
		1.3	
		277	
		111	
Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C

■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$R_{\theta JA}$	30	36	°C/W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.35	0.45	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJN280G10H	B1	YJN280G10H	30	360	1800	Tube



YJN280G10H

■ Electrical Characteristics ($T_J=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$	-	-	1	μA
		$V_{DS}=100V, V_{GS}=0V, T_J=150^\circ C$	-	-	100	
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	2.8	4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=50A$	-	2	2.6	$m\Omega$
		$V_{GS}=10V, I_D=20A$	-	2	2.6	
		$V_{GS}=6V, I_D=20A$	-	2.2	3.0	
Diode Forward Voltage	V_{SD}	$I_S=50A, V_{GS}=0V$	-	-	1.2	V
Gate resistance	R_G	$f=1MHz$	-	1	-	Ω
Maximum Body-Diode Continuous Current	I_S		-	-	280	A
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	-	13600	-	pF
Output Capacitance	C_{oss}		-	4000	-	
Reverse Transfer Capacitance	C_{rss}		-	110	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=50V, I_D=140A$	-	257	-	nC
Gate-Source Charge	Q_{gs}		-	89	-	
Gate-Drain Charge	Q_{gd}		-	88	-	
Reverse Recovery Charge	Q_{rr}	$I_F=140A, dI/dt=100A/us$	-	374	-	nC
Reverse Recovery Time	t_{rr}		-	162	-	
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DD}=50V, I_D=140A$ $R_{GEN}=2.2\Omega$	-	51	-	ns
Turn-on Rise Time	t_r		-	158	-	
Turn-off Delay Time	$t_{D(off)}$		-	98	-	
Turn-off fall Time	t_f		-	52	-	

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B. $T_J=25^\circ C, V_{DD}=50V, V_G=10V, R_G=25\Omega, L=5mH, IAS=15A$.
- C. P_d is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of R_{GJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.



■Typical Electrical and Thermal Characteristics Diagrams

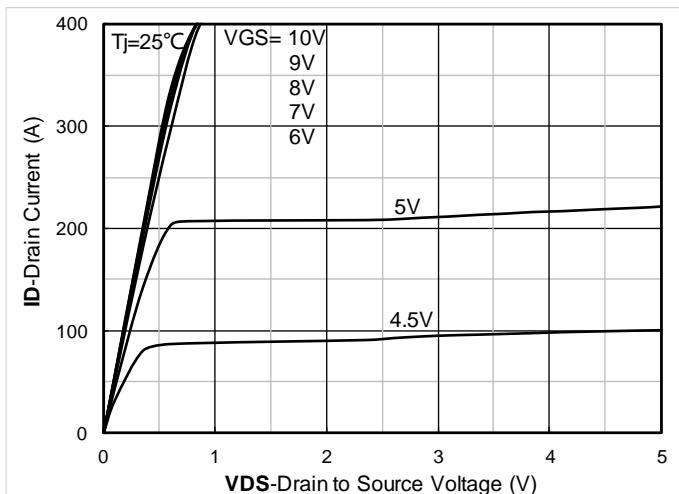


Figure 1. Output Characteristics

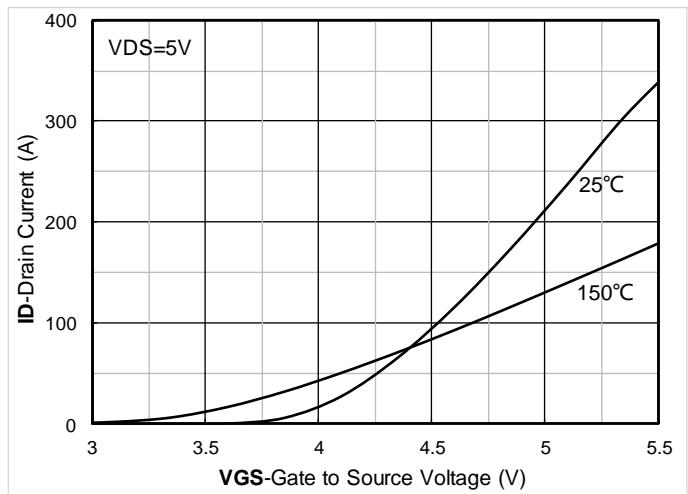


Figure 2. Transfer Characteristics

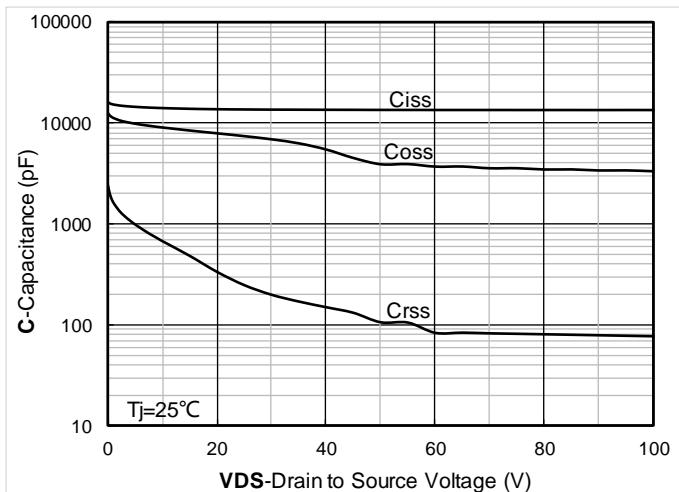


Figure 3. Capacitance Characteristics

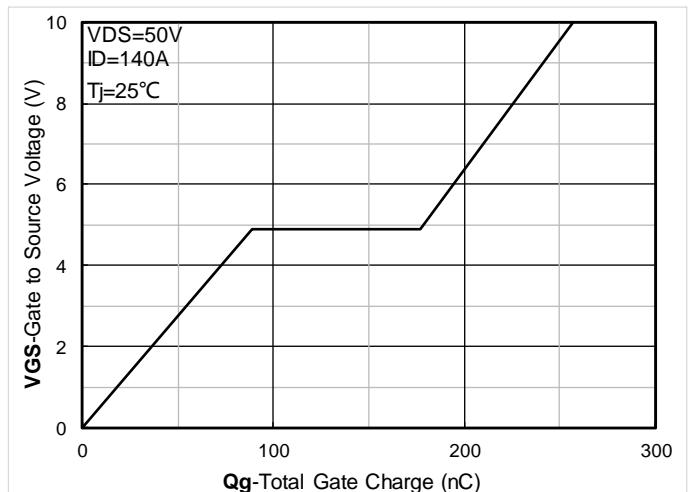


Figure 4. Gate Charge

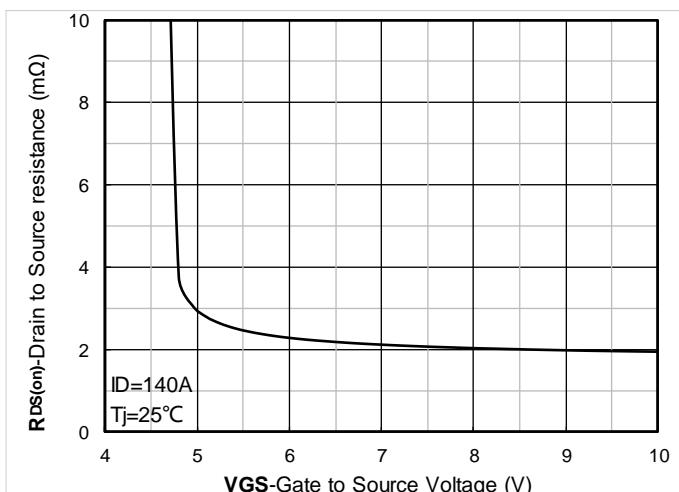


Figure 5. On-Resistance vs Gate to Source Voltage

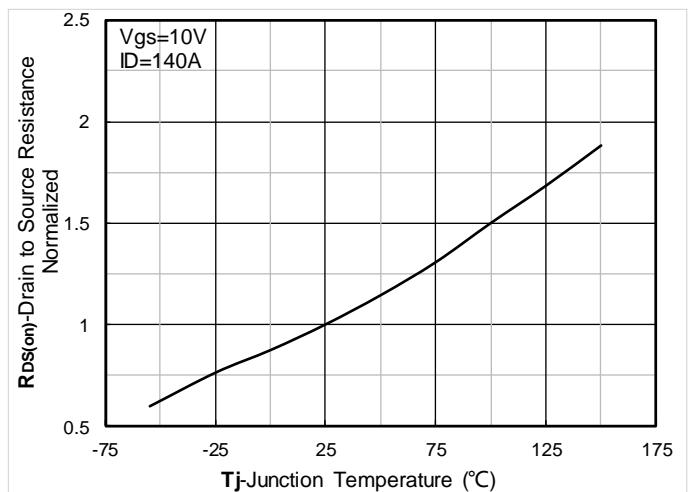


Figure 6. Normalized On-Resistance

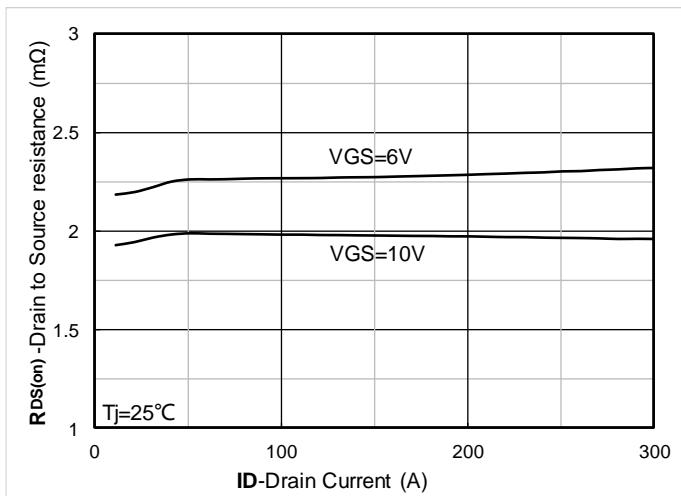


Figure 7. RDS(on) VS Drain Current

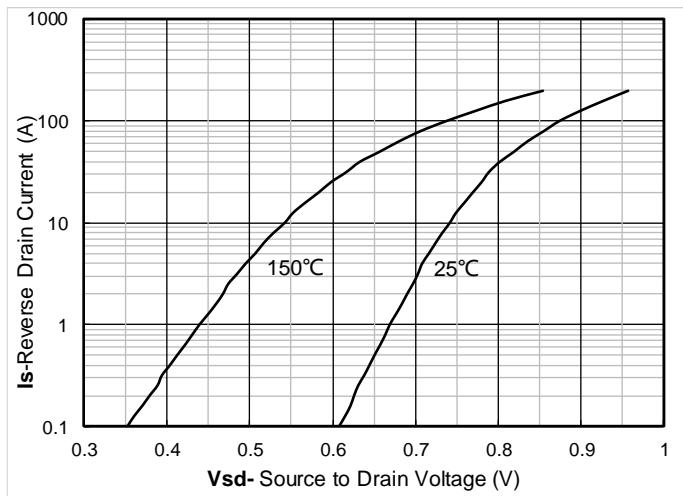


Figure 8. Forward characteristics of reverse diode

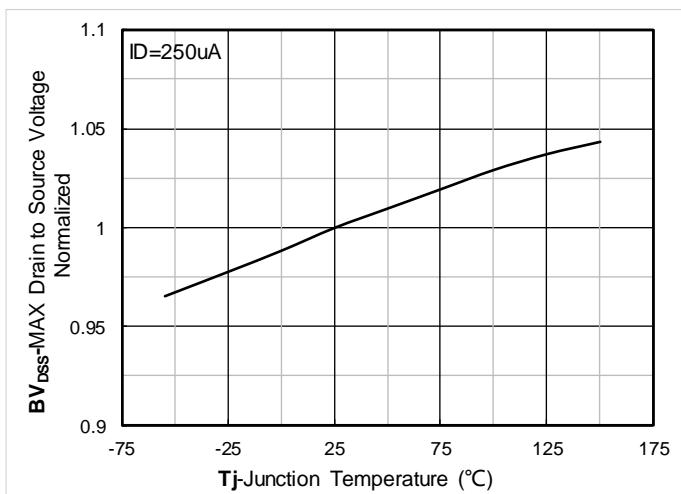


Figure 9. Normalized breakdown voltage

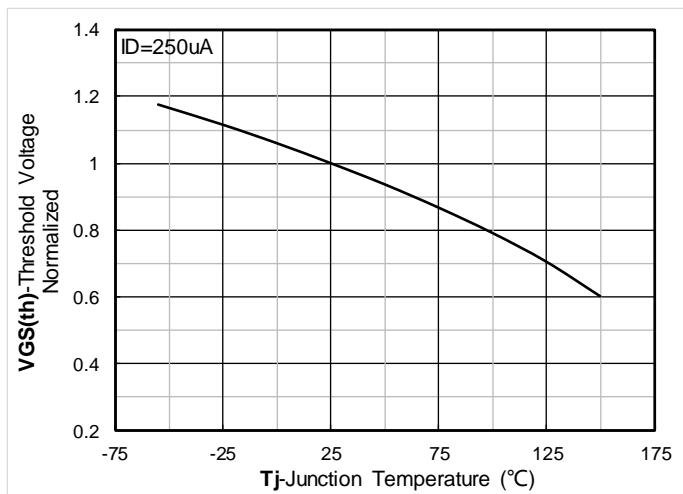


Figure 10. Normalized Threshold voltage

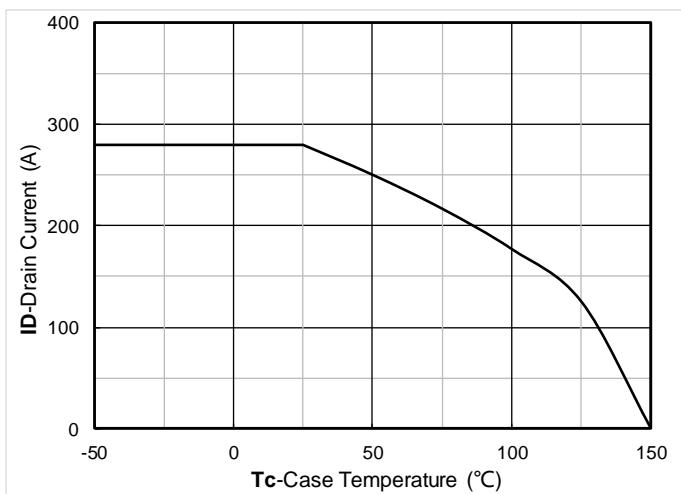


Figure 11. Current dissipation

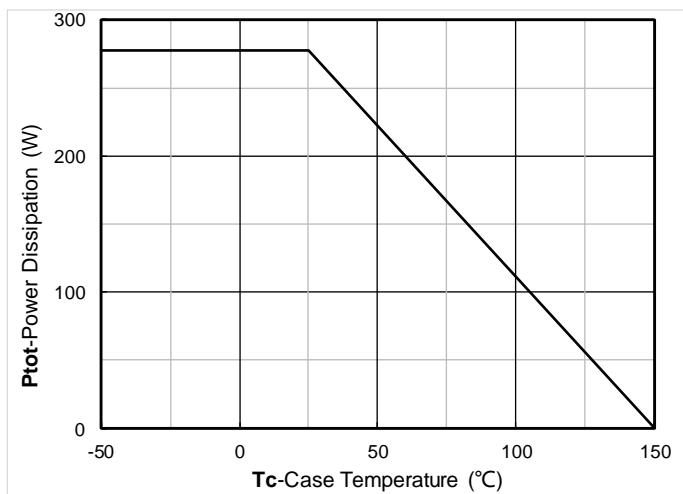


Figure 12. Power dissipation

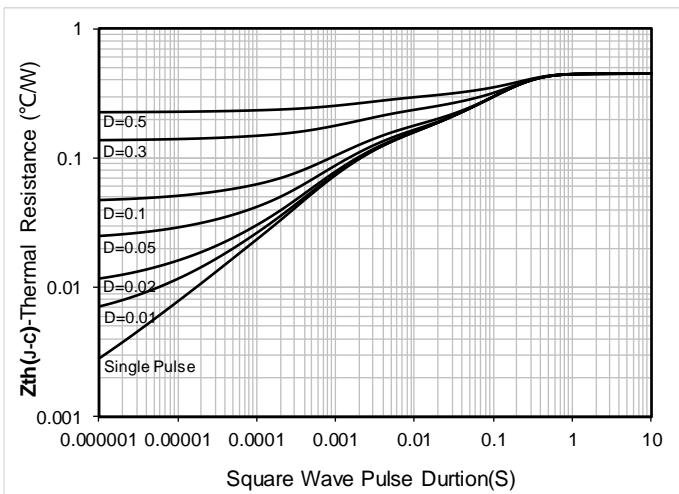


Figure 13. Maximum Transient Thermal Impedance

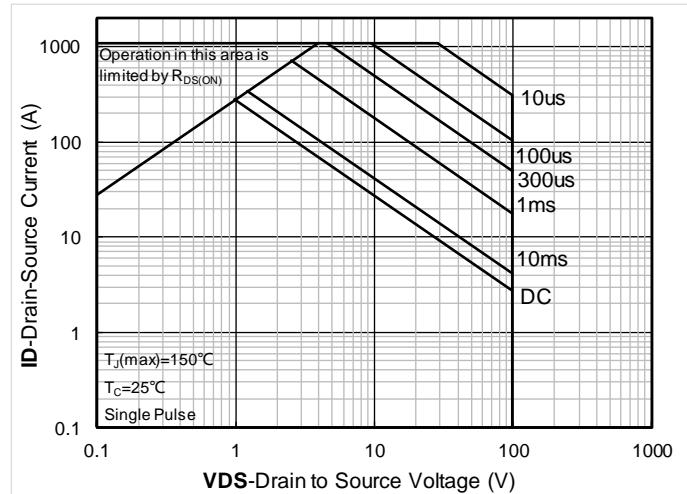


Figure 14. Safe Operation Area

■ Test Circuits & Waveforms

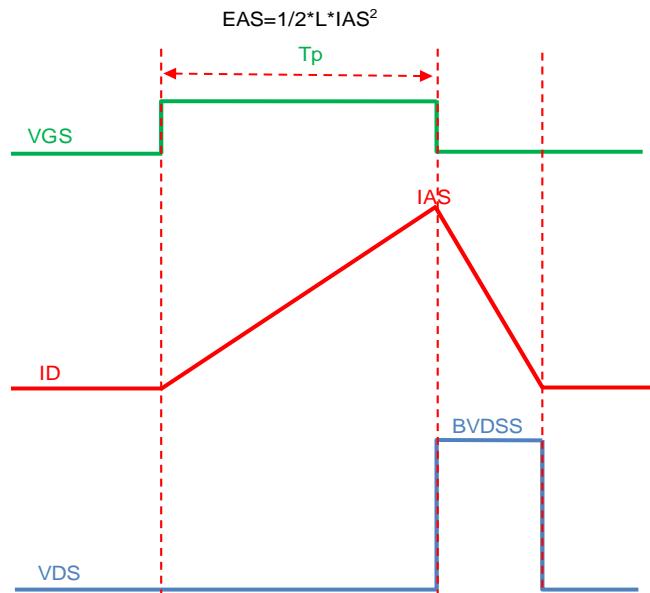
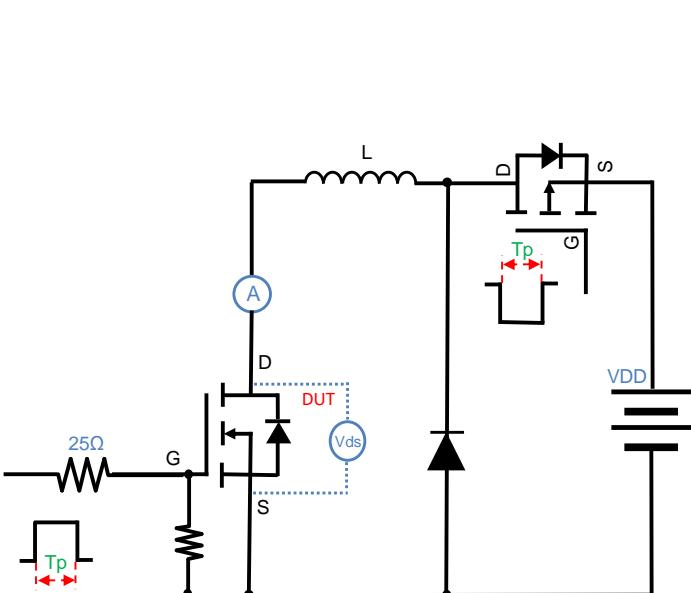


Figure A. Unclamped Inductive Switching (UIS) Test Circuit & Waveform

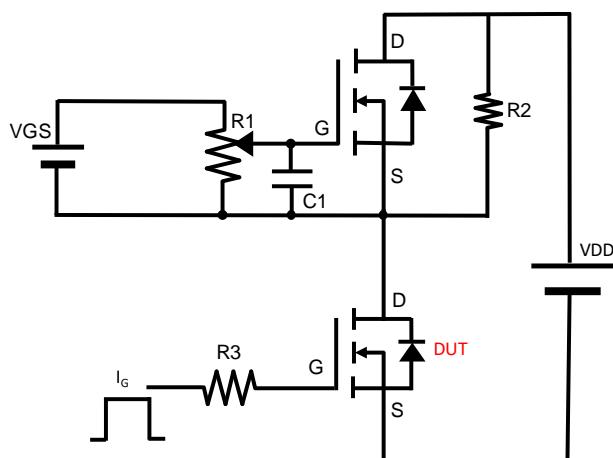


Figure B. Gate Charge Test Circuit & Waveform

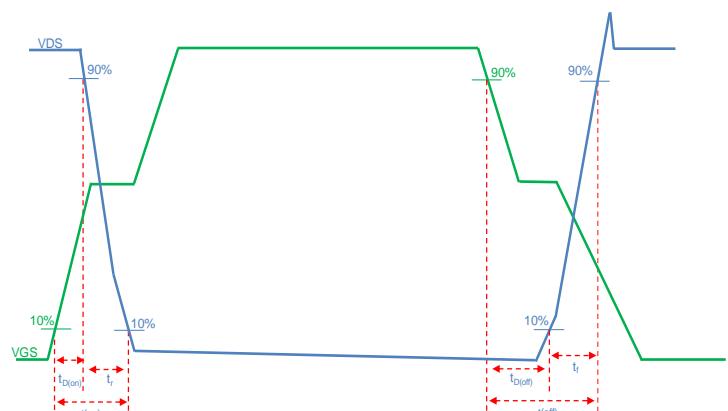
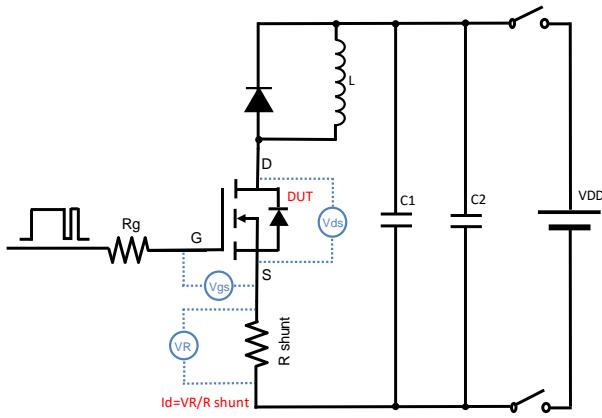
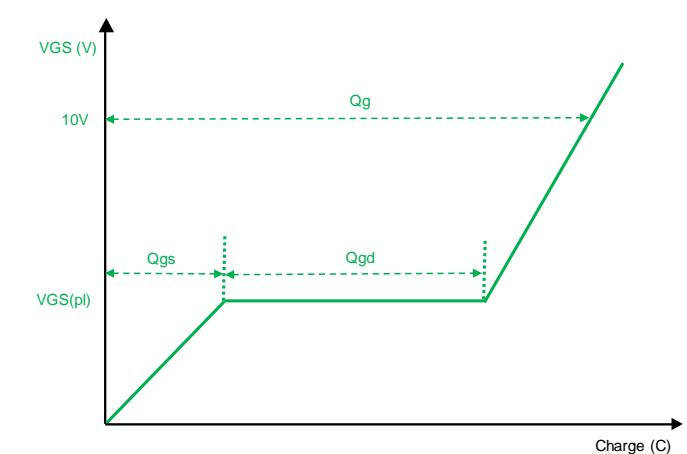


Figure C. Resistive Switching Test Circuit & Waveform

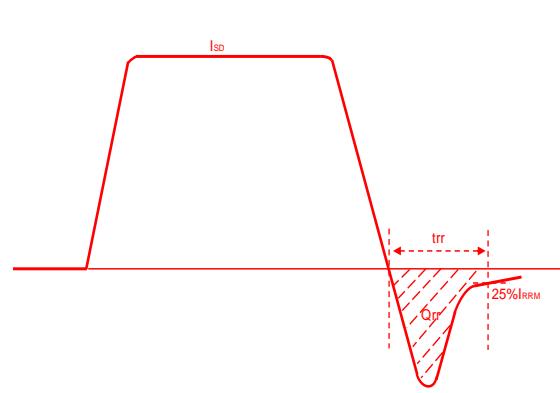
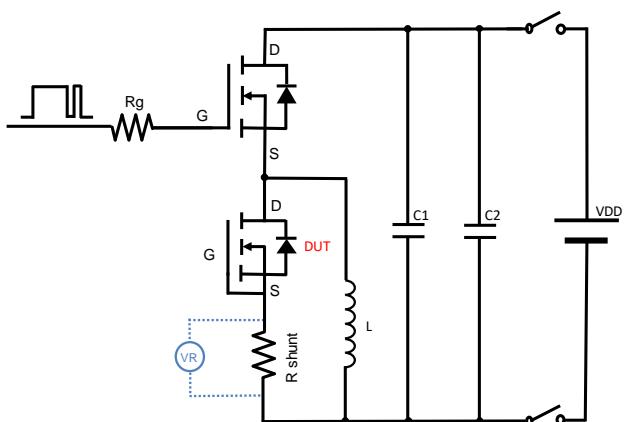
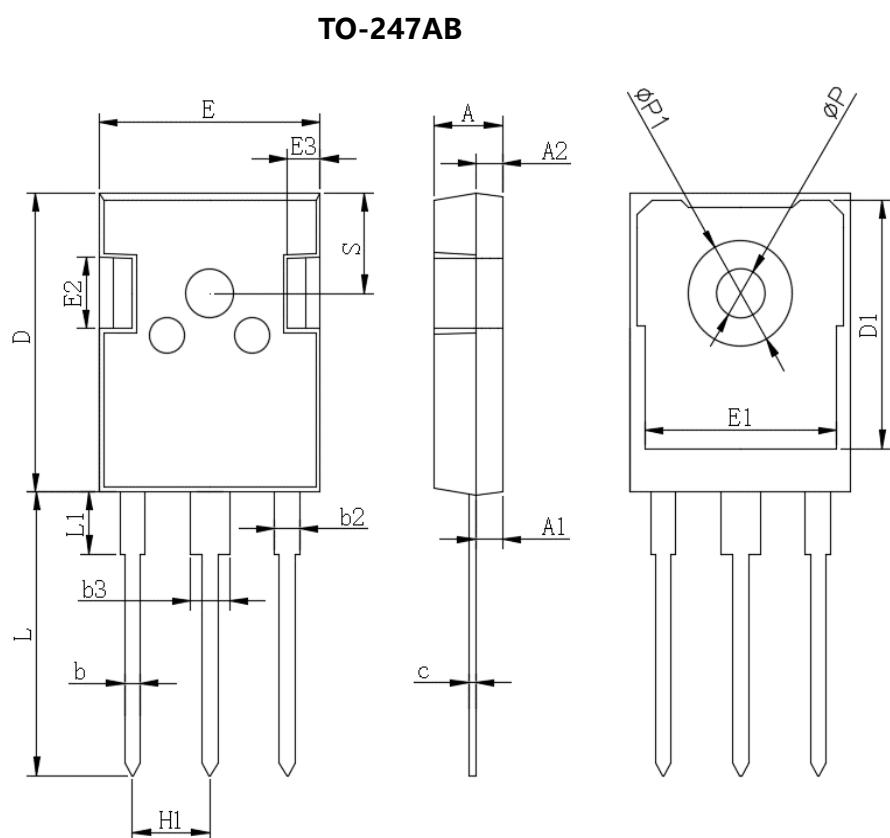


Figure D. Diode Recovery Test Circuit & Waveform



■ TO-247AB Package information



TO-247AB		
Dim	Min	Max
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
c	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ϕP	3.40	3.80
ϕP_1	-	7.30
S	6.15TYP	
H1	5.44TYP	
b3	2.80	3.20



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